NPN Silicon Power Transistor

High Voltage SWITCHMODE™ Series

Designed for use in electronic ballast (light ballast) and in Switchmode Power supplies up to 50 Watts.

Features

- Improved Efficiency Due to:
 - Low Base Drive Requirements (High and Flat DC Current Gain hFF)
 - Low Power Losses (On-State and Switching Operations)
 - Fast Switching: $t_{fi} = 100 \text{ ns (typ)}$ and $t_{si} = 3.2 \mu \text{s (typ)}$
 - @ $I_C = 2.0 \text{ A}$, $I_{B1} = I_{B2} = 0.4 \text{ A}$
- Full Characterization at 125°C
- Tight Parametric Distributions Consistent Lot-to-Lot
- Pb-Free Package is Available*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector–Emitter Sustaining Voltage	V _{CEO}	400	Vdc
Collector-Base Breakdown Voltage	V _{CES}	700	Vdc
Emitter-Base Voltage	V _{EBO}	9.0	Vdc
Collector Current – Continuous – Peak (Note 1)	I _C	5.0 10	Adc
Base Current	I _B	2.0	Adc
Total Device Dissipation @ T _C = 25°C Derate above 25°C	P _D	75 0.6	W W/°C
Operating and Storage Temperature	T _J , T _{stg}	-65 to 150	°C

THERMAL CHARACTERISTICS

Characteristics	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.65	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	°C/W

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

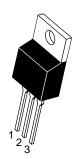
1. Pulse Test: Pulse Width = 5 ms, Duty Cycle ≤ 10%.



ON Semiconductor®

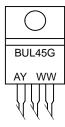
http://onsemi.com

POWER TRANSISTOR 5.0 AMPERES, 700 VOLTS, 35 AND 75 WATTS



TO-220AB CASE 221A-09 STYLE 1

MARKING DIAGRAM



BUL45 = Device Code A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
BUL45	TO-220	50 Units / Rail
BUL45G	TO-220 (Pb-Free)	50 Units / Rail

^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

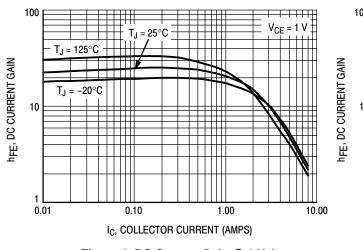
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BUL45

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

看信的CALCHARACTE	KISTICS (1 _C = 25	C unless	otherwise noted)		ı		Γ	Γ
Characteristic			Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS								
Collector-Emitter Sustaining Vo	oltage (I _C = 100 mA	L = 25 m	nH)	V _{CEO(sus)}	400	-	-	Vdc
Collector Cutoff Current (V _{CE} =	Rated V_{CEO} , $I_B = 0$)		I _{CEO}	_	-	100	μAdc
Collector Cutoff Current (V _{CE} =	Rated V_{CES} , $V_{EB} =$	0) (T _C = 125	э°С)	I _{CES}	- -	-	10 100	μAdc
Emitter Cutoff Current (V _{EB} = 9	.0 Vdc, I _C = 0)			I _{EBO}	-	-	100	μAdc
ON CHARACTERISTICS					•	•		
Base–Emitter Saturation Voltag ($I_C = 1.0$ Adc, $I_B = 0.2$ Adc ($I_C = 2.0$ Adc, $I_B = 0.4$ Adc	()			V _{BE(sat)}		0.84 0.89	1.2 1.25	Vdc
Collector-Emitter Saturation Vo		$I_B = 0.2 I_C$ $T_C = 125$		V _{CE(sat)}	- -	0.175 0.150	0.25	Vdc
Collector-Emitter Saturation Vo	oltage (I _C = 2.0 Adc,	$I_B = 0.4 R$ $T_C = 125$	Adc)	V _{CE(sat)}	_ _	0.25 0.275	0.4	Vdc
DC Current Gain (I _C = 0.3 Adc,	V _{CE} = 5.0 Vdc)			h _{FE}	14	_	34	_
$(I_C = 2.0 \text{ Adc}, V_{CF} = 1.0 \text{ V})$		$(T_C = 125)$	5°C)		- 7.0	32 14	_	
, 0	,	$T_{\rm C} = 125$	i°C)		5.0	12	_	
$(I_C = 10 \text{ mAdc}, V_{CE} = 5.0)$	Vdc)				10	22	-	
DYNAMIC CHARACTERISTIC				T	T	1	Т	Т
Current Gain Bandwidth (I _C = 0			MHz)	f _T	-	12	_	MHz
Output Capacitance (V _{CB} = 10	Vdc, $I_E = 0$, $f = 1.0$	MHz)		C _{ob}	-	50	75	pF
Input Capacitance (V _{EB} = 8.0 V	(dc)			C _{ib}	-	920	1200	pF
	(I _C = 1.0 Adc I _{B1} = 100 mAdc V _{CC} = 300 V)	1.0 μs	(T _C = 125°C)	V _{CE} (Dyn sat)	_ _	1.75 4.4	-	· Vdc
Dynamic Saturation Voltage: Determined 1.0 μs and 3.0 μs		3.0 μs	(T _C = 125°C)		- -	0.5 1.0	- -	
respectively after rising I _{B1} reaches 90% of final I _{B1}	(I _C = 2.0 Adc I _{B1} = 400 mAdc V _{CC} = 300 V)	1.0 μs	(T _C = 125°C)		_ _	1.85 6.0	-	
(see Figure 18)		3.0 μs	(T _C = 125°C)		_ _	0.5 1.0	-	
SWITCHING CHARACTERIST	ICS: Resistive Loa	d					_	_
Turn-On Time	(I _C = 2.0 Adc, I _{B1} Pulse Width = 20	= I _{B2} = 0. μs,	4 Adc (T _C = 125°C)	t _{on}	- -	75 120	110 -	ns
Turn-Off Time	Duty Cycle < 20% V _{CC} = 300 V (T _C = 125°C)			t _{off}	_ _	2.8 3.5	3.5	μs
SWITCHING CHARACTERIST	ICS: Inductive Loa	d (V _{CC} =	15 Vdc, L _C = 200	μH, V _{clamp} = 3	00 Vdc)	•		
Fall Time	$(I_C = 2.0 \text{ Adc}, I_{B1} $ $I_{B2} = 0.4 \text{ Adc})$	(I _C = 2.0 Adc, I _{B1} = 0.4 Adc			70 -	_ 200	170 -	ns
Storage Time		$(T_C = 125^{\circ}C)$			2.6 -	- 4.2	3.8	μS
Crossover Time	$(T_C = 125 ^{\circ}C)$			t _c	_ _	230 400	350 -	ns
Fall Time	$(I_C = 1.0 \text{ Adc}, I_{B1} = 100 \text{ mAdc}$ $I_{B2} = 0.5 \text{ Adc})$ $(T_C = 125^{\circ}\text{C})$			t _{fi}	_ _	110 100	150 -	ns
Storage Time	(T _C = 125°C)			t _{si}	_ _	1.1 1.5	1.7	μs
Crossover Time	$(T_C = 125^{\circ}C)$			t _c	_ _	170 170	250 -	ns
Fall Time	$(I_C = 2.0 \text{ Adc}, I_{B1} = 250 \text{ mAdc} $ $I_{B2} = 2.0 \text{ Adc})$ $(T_C = 125^{\circ}\text{C})$			t _{fi}	_	80	120	ns
Storage Time	$(T_C = 125^{\circ}C)$			t _{si}	_	0.6	0.9	μs
Crossover Time	$(T_C = 125^{\circ}C)$			t _C	_	175	300	ns

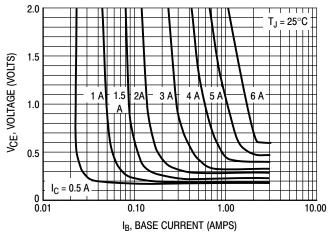
TYPICAL STATIC CHARACTERISTICS



 $T_{J} = 125^{\circ}C$ $T_{J} = 125^{\circ}C$ $T_{J} = -20^{\circ}C$ $T_{J} = -20$

Figure 1. DC Current Gain @ 1 Volt

Figure 2. DC Current Gain at @ 5 Volts



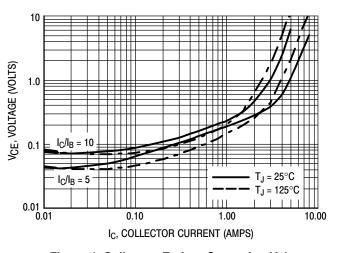
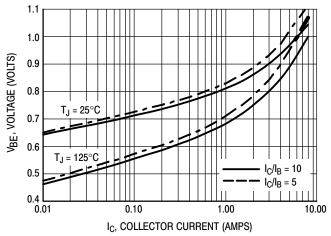


Figure 3. Collector-Emitter Saturation Region

Figure 4. Collector-Emitter Saturation Voltage



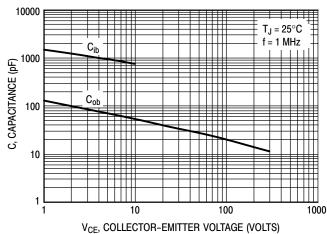
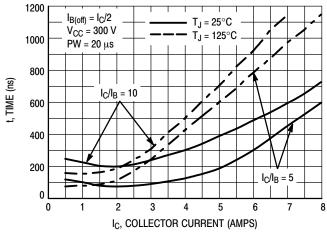


Figure 5. Base-Emitter Saturation Region

Figure 6. Capacitance

TYPICAL SWITCHING CHARACTERISTICS $(I_{B2} = I_C/2 \text{ for all switching})$



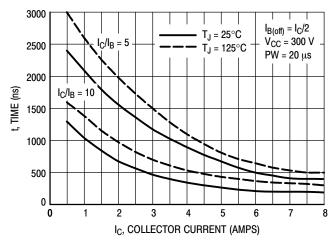
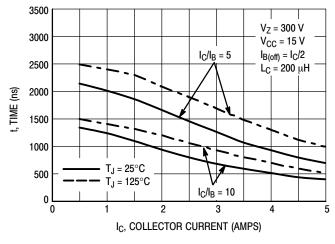


Figure 7. Resistive Switching, ton

Figure 8. Resistive Switching, toff



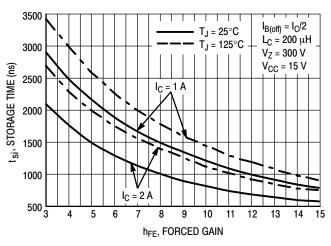
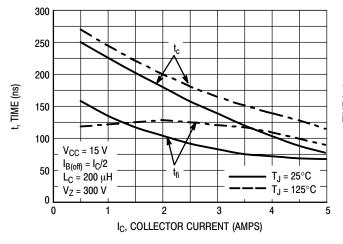


Figure 9. Inductive Storage Time, tsi

Figure 10. Inductive Storage Time, t_{si}(h_{FE})



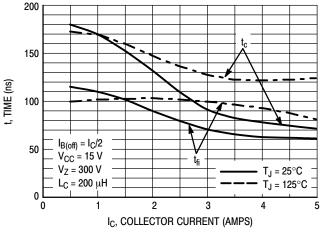
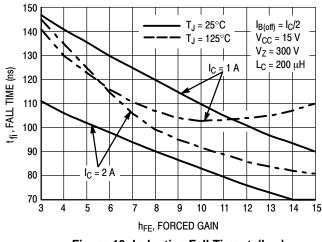


Figure 11. Inductive Switching, t_c & t_{fi} , $I_C/I_B = 5$

Figure 12. Inductive Switching, $t_c \& t_{fi}$, $I_C/I_B = 10$

TYPICAL SWITCHING CHARACTERISTICS $(I_{B2} = I_C/2 \text{ for all switching})$



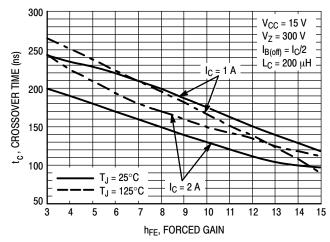


Figure 13. Inductive Fall Time, tfi(hFE)

Figure 14. Crossover Time

GUARANTEED SAFE OPERATING AREA INFORMATION

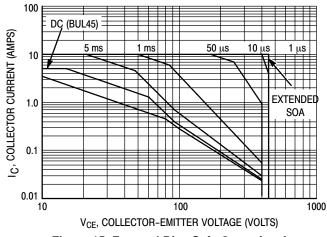


Figure 15. Forward Bias Safe Operating Area

Figure 16. Reverse Bias Switching Safe Operating Area

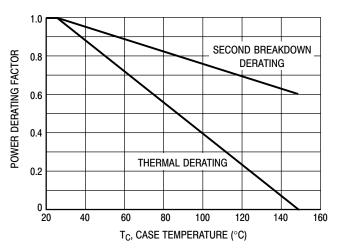
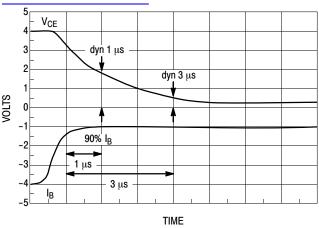


Figure 17. Forward Bias Power Derating

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate. The data of Figure 15 is based on $T_C = 25^{\circ}C$; $T_{J(pk)}$ is variable depending on power level. Second breakdown pulse limits are valid for duty cycles to 10% but must be derated when $T_C \ge 25$ °C. Second breakdown limitations do not derate the same as thermal limitations. Allowable current at the voltages shown in Figure 15 may be found at any case temperature by using the appropriate curve on Figure 17. T_{J(pk)} may be calculated from the data in Figures 20. At any case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown. For inductive loads, high voltage and current must be sustained simultaneously during turn-off with the base-to-emitter junction reverse-biased. The safe level is specified as a reverse-biased safe operating area (Figure 16). This rating is verified under clamped conditions so that the device is never subjected to an avalanche mode.



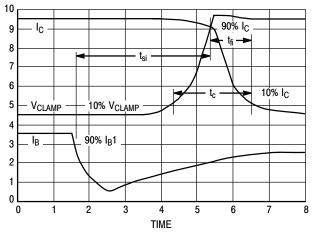


Figure 18. Dynamic Saturation Voltage Measurements

Figure 19. Inductive Switching Measurements

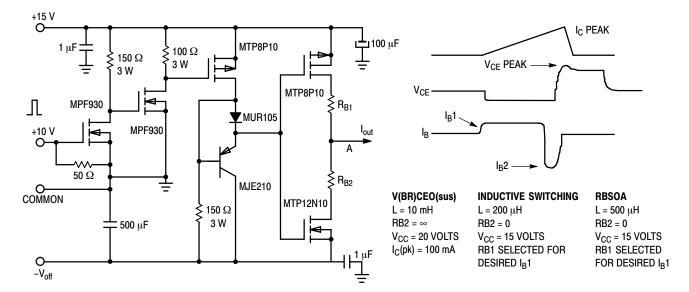


Table 1. Inductive Load Switching Drive Circuit

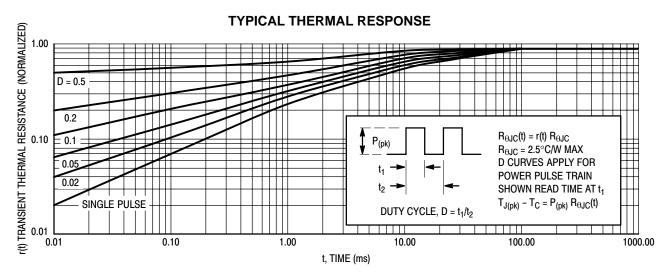


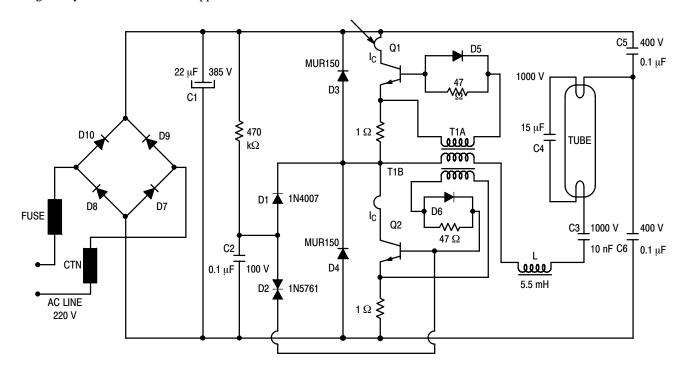
Figure 20. Typical Thermal Response ($Z_{\theta JC}(t)$) for BUL45

The BUL45 Ripolar Power Transistors were specially designed for use in electronic lamp ballasts. A circuit designed by ON Semiconductor applications was built to

Secondaries: T1A: 4 turns

T1B: 4 turns

demonstrate how well these devices operate. The circuit and detailed component list are provided below.



Components Lists

Q1 =	Q2 = BUL45 Transistor	All resistors are 1/4 Watt, ±5%		
D1 =	1N4007 Rectifier	R1 =	470 kΩ	
D2 =	1N5761 Rectifier	R2 =	$R3 = 47 \Omega$	
D3 =	D4 = MUR150	R4 =	R5 = 1 Ω (these resistors are optional, and	
D5 =	D6 = MUR105		might be replaced by a short circuit)	
D7 =	D8 = D9 = D10 = 1N400	C1 =	22 μF/385 V	
CTN =	47 Ω @ 25°C	C2 =	0.1 μF	
L =	RM10 core, A1 = 400, B51 (LCC) 75 turns,	C3 =	10 nF/1000 V	
	wire $\emptyset = 0.6 \text{ mm}$	C4 =	15 nF/1000 V	
T1 =	FT10 toroid, T4A (LCC)	C5 =	$C6 = 0.1 \mu F/400 V$	
	Primary: 4 turns			

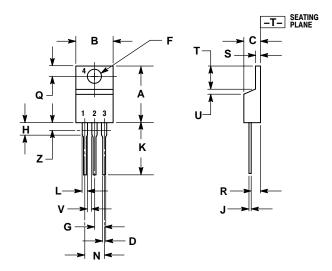
NOTES:

- 1. Since this design does not include the line input filter, it cannot be used "as-is" in a practical industrial circuit.
- 2. The windings are given for a 55 Watt load. For proper operation they must be re-calculated with any other loads.

Figure 21. Application Example

PACKAGE DIMENSIONS

TO-220AB CASE 221A-09 **ISSUE AA**



- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
 DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.018	0.025	0.46	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z		0.080		2.04

STYLE 1:

PIN 1. BASE

- 2. COLLECTOR
- 3. EMITTER
- 4. COLLECTOR

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